

Docket No.: M4065.0226/P226  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Tongbi Jiang

Application No.: 09/484,437

Confirmation No.: 9698

Filed: January 18, 2000

Art Unit: 2813

For: Die attach curing method for semiconductor  
device

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Examiner: J. M. Mitchell

**AMENDMENT AFTER FILING OF REQUEST FOR CONTINUED EXAMINATION**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

Further to Applicant's filing of a Request for Continued Examination along with the necessary fees, please consider the following Amendments.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 6 of this paper.